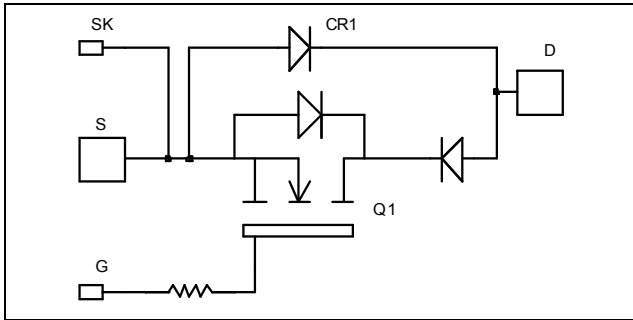


*Single switch
Series & parallel diodes
MOSFET Power Module*

**$V_{DSS} = 200V$
 $R_{DSon} = 5m\Omega$ max @ $T_j = 25^\circ C$
 $I_D = 317A$ @ $T_c = 25^\circ C$**



Application

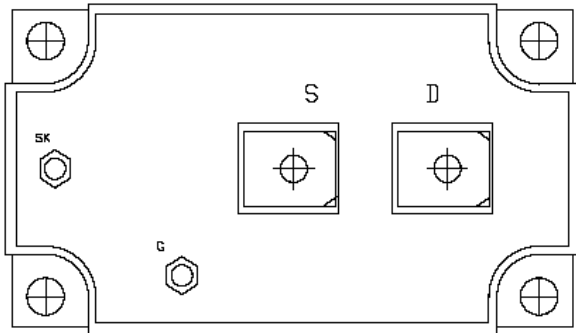
- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Low stray inductance
 - M6 power connectors
 - M4 signal connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit	
V_{DSS}	Drain - Source Breakdown Voltage	200	V	
I_D	Continuous Drain Current	$T_c = 25^\circ C$	A	
		$T_c = 80^\circ C$		237
I_{DM}	Pulsed Drain current	1268		
V_{GS}	Gate - Source Voltage	± 30	V	
R_{DSon}	Drain - Source ON Resistance	5	$m\Omega$	
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	1136	W
I_{AR}	Avalanche current (repetitive and non repetitive)	89	A	
E_{AR}	Repetitive Avalanche Energy	50	mJ	
E_{AS}	Single Pulse Avalanche Energy	2500		

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
BV_{DSS}	Drain - Source Breakdown Voltage	$V_{GS} = 0V, I_D = 500\mu A$	200			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 200V$ $T_j = 25^\circ\text{C}$			200	μA
		$V_{GS} = 0V, V_{DS} = 160V$ $T_j = 125^\circ\text{C}$			1000	
$R_{DS(on)}$	Drain - Source on Resistance	$V_{GS} = 10V, I_D = 158.5A$			5	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 10mA$	3		5	V
I_{GSS}	Gate - Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 200	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1MHz$		27.4		nF
C_{oss}	Output Capacitance			8.7		
C_{rss}	Reverse Transfer Capacitance			0.4		
Q_g	Total gate Charge	$V_{GS} = 10V$ $V_{Bus} = 100V$ $I_D = 300A$		448		nC
Q_{gs}	Gate - Source Charge			172		
Q_{gd}	Gate - Drain Charge			188		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 133V$ $I_D = 300A$ $R_G = 1.2\Omega$		28		ns
T_r	Rise Time			56		
$T_{d(off)}$	Turn-off Delay Time			81		
T_f	Fall Time			99		
E_{on}	Turn-on Switching Energy ①	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 300A, R_G = 1.2\Omega$		1852		μJ
E_{off}	Turn-off Switching Energy ②			1820		
E_{on}	Turn-on Switching Energy ①	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 300A, R_G = 1.2\Omega$		2432		μJ
E_{off}	Turn-off Switching Energy ②			2124		

① E_{on} includes diode reverse recovery.

② In accordance with JEDEC standard JESD24-1.

Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle $T_c = 85^\circ\text{C}$		120		A
V_F	Diode Forward Voltage	$I_F = 120A$		1.1	1.15	V
		$I_F = 240A$		1.4		
		$I_F = 120A$ $T_j = 125^\circ\text{C}$		0.9		
t_{rr}	Reverse Recovery Time	$I_F = 120A$ $V_R = 133V$ $di/dt = 400A/\mu s$ $T_j = 25^\circ\text{C}$		31		ns
		$T_j = 125^\circ\text{C}$		60		
Q_{rr}	Reverse Recovery Charge	$I_F = 120A$ $V_R = 133V$ $di/dt = 400A/\mu s$ $T_j = 25^\circ\text{C}$		120		nC
		$T_j = 125^\circ\text{C}$		500		

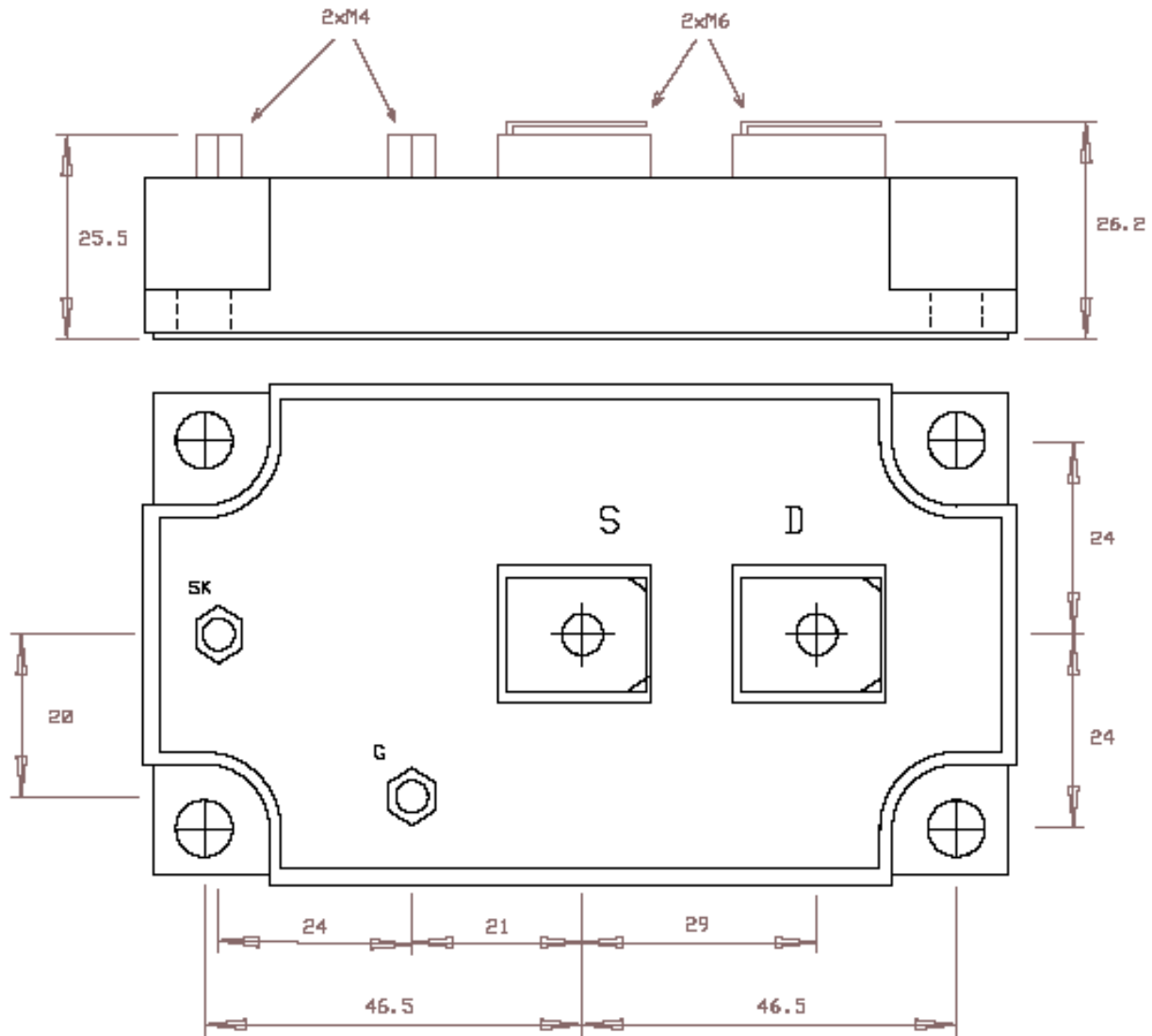
Parallel diode ratings and characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle	$T_c = 90^\circ\text{C}$		100		A
V_F	Diode Forward Voltage	$I_F = 100\text{A}$			1	1.1	V
		$I_F = 200\text{A}$			1.4		
		$I_F = 100\text{A}$	$T_j = 125^\circ\text{C}$		0.9		
t_{rr}	Reverse Recovery Time	$I_F = 100\text{A}$	$T_j = 25^\circ\text{C}$		60		ns
		$V_R = 133\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		110		
Q_{rr}	Reverse Recovery Charge	$I_F = 100\text{A}$	$T_j = 25^\circ\text{C}$		200		nC
		$V_R = 133\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		840		

Thermal and package characteristics

<i>Symbol</i>	<i>Characteristic</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R_{thJC}	Junction to Case	Transistor			0.11	$^\circ\text{C}/\text{W}$
		Series diode			0.46	
		Parallel diode			0.6	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$, $I_{isol} < 1\text{mA}$, 50/60Hz		2500			V
T_J	Operating junction temperature range		-40		150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-40		125	
T_C	Operating Case Temperature		-40		100	
Torque	Mounting torque	M4			1.2	N.m
		M6	3		5	
Wt	Package Weight				400	g

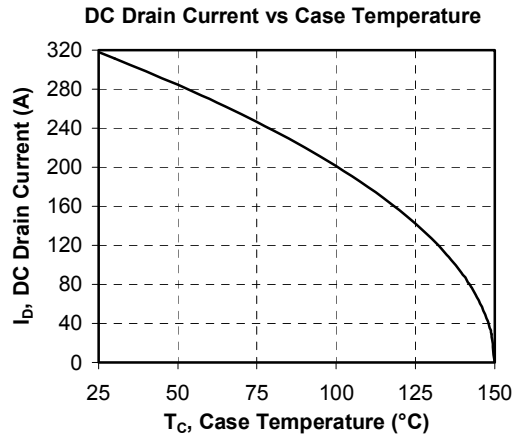
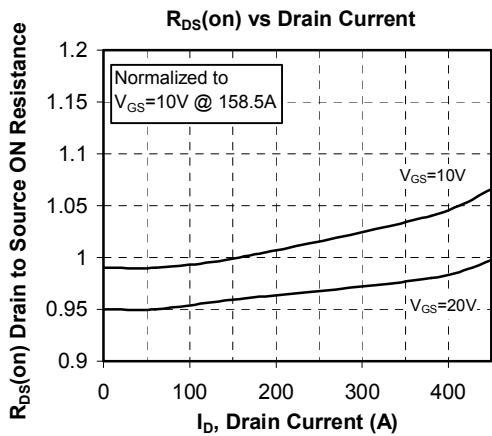
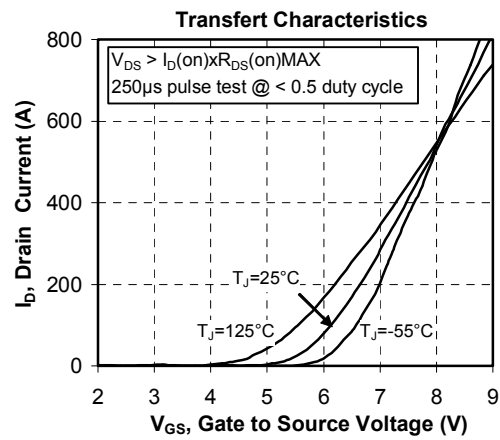
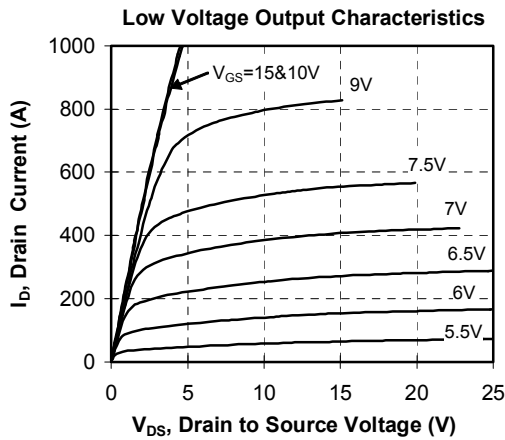
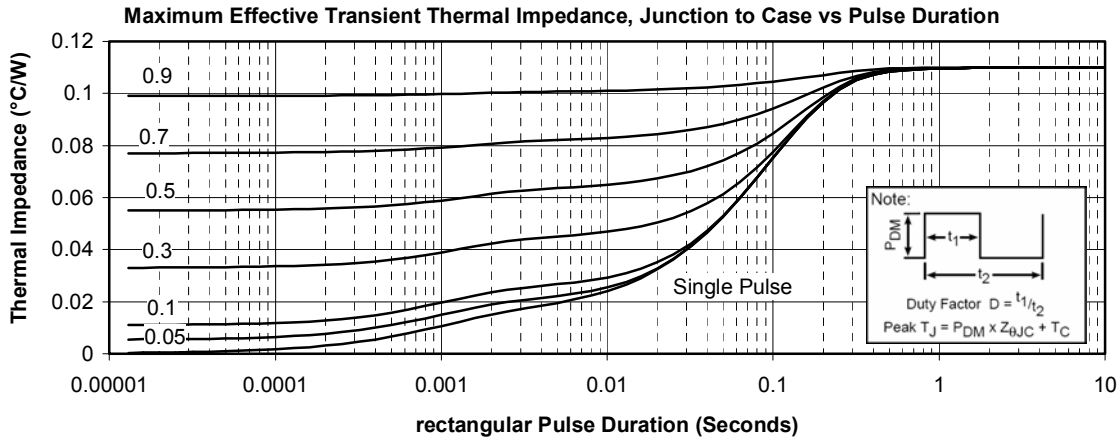
Package outline

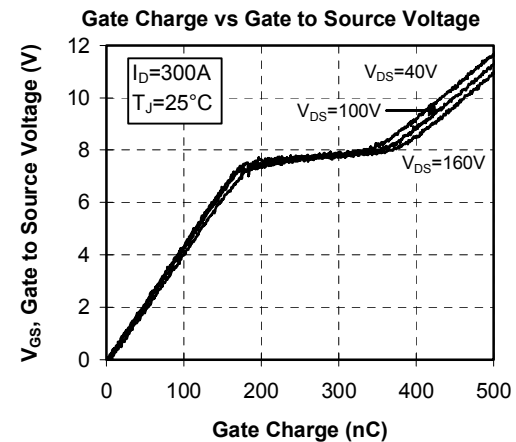
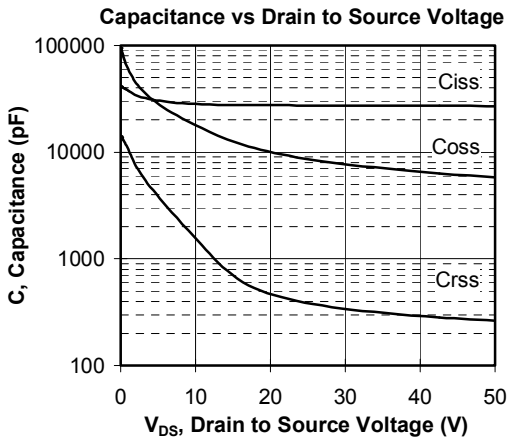
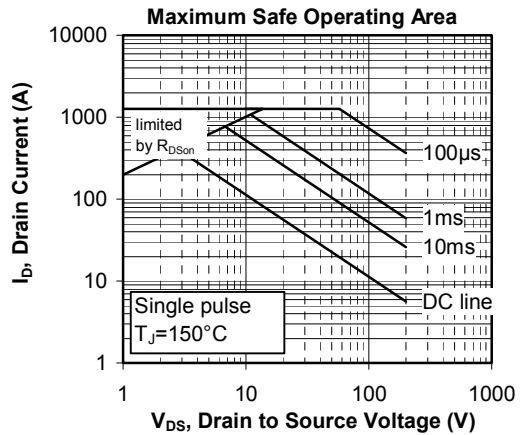
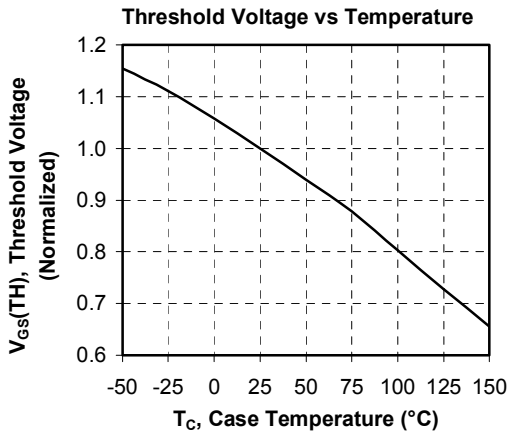
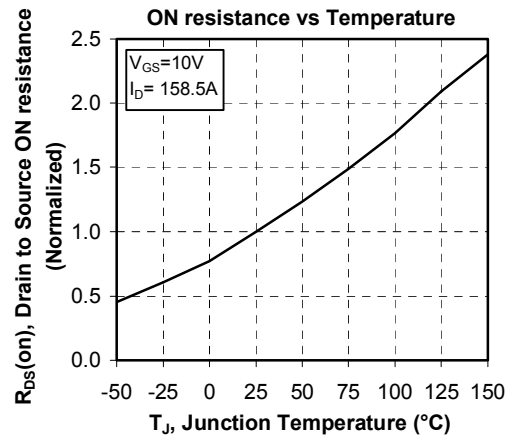
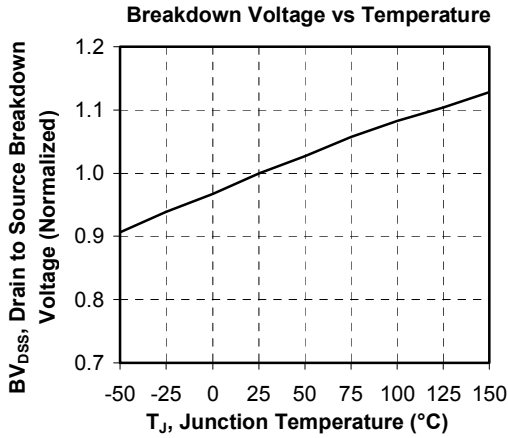


GENERAL TOLERANCES : +/-0.5mm

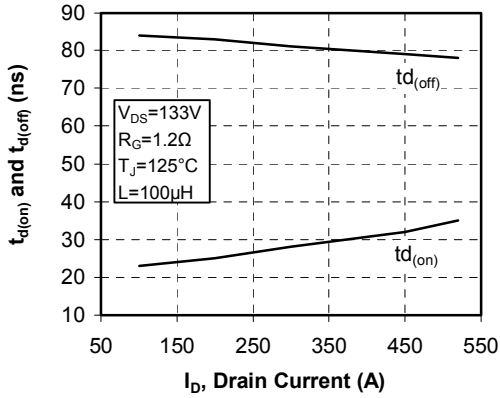
Mounting holes: 4xØ6.5 mm

Typical Performance Curve

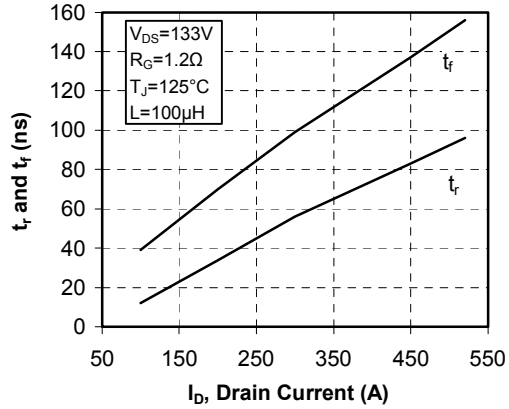




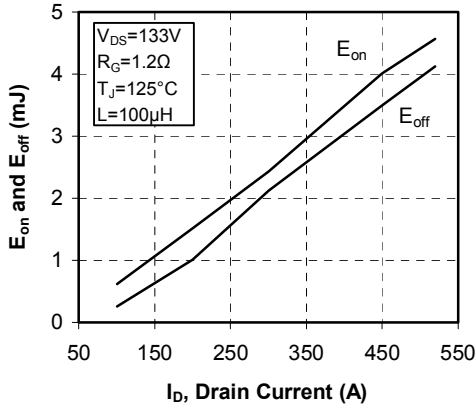
Delay Times vs Current



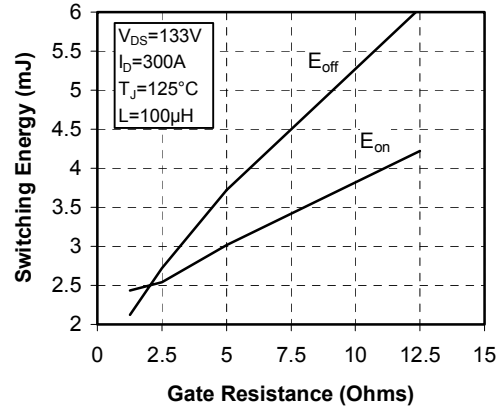
Rise and Fall times vs Current



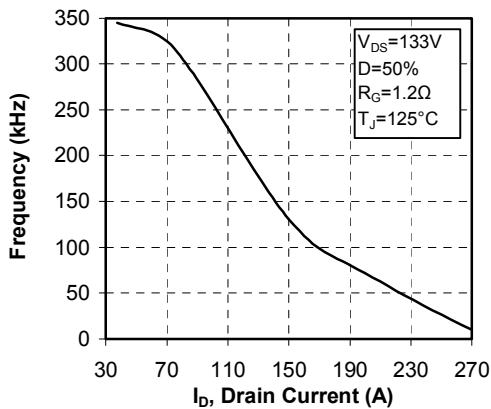
Switching Energy vs Current



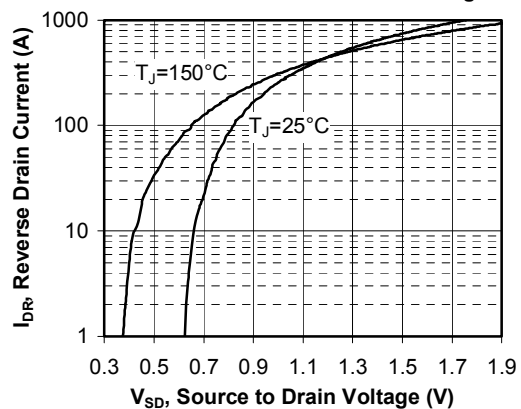
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



APT reserves the right to change, without notice, the specifications and information contained herein

APT's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.